BGA Heat Sink - High Performance ASIC Cooling



ATS Part#:

Description:

ATS-56007-C1-R0

45.00 x 45.00 x 15.00 mm BGA Heat Sink - High Performance ASIC Cooling

Heat Sink Type: Heat Sink Attachment: Equivalent Part Number: ATS-56007-C3-R0

ASIC Cooling **Thermal Tape**

*Image above is for illustration purpose only.

Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling .
- Designed specifically for ASIC package and their unique cooling requirements •
- Comes preassembled with high performance thermal interface material •

Thermal Performance

		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	2.4 °C/W	2 °C/W	1.7 °C/W	1.5 °C/W	1.3 °C/W	1.2 °C/W	1.1 °C/W
	Ducted Flow	1.7	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	45.00 mm	45.00 mm	15.00 mm	64 mm	T412	BLACK-ANODIZED
	component size. < height from the bottom of the base to the top of the fin field. cact heat sink assembly with an equivalent thermal interface material are provided for reference only. Actual performance may vary by odate or change its products without notice to improve the design or sink assembly is RoHS-6 and REACH compliant. custom options available.					
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For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.



